



# SOT1996-1

HLFLGA21, thermal enhanced low profile fine-pitch land grid array package, 21 terminals, 0.9 mm pitch, 6.2 mm x 6.2 mm x 1.148 mm body

2 July 2021

Package information

## 1 Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	HLFLGA21
<b>Package style descriptive code</b>	HLLGA (thermal enhanced low profile land grid array)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	29-08-2018
<b>Manufacturer package code</b>	98ASA01306D

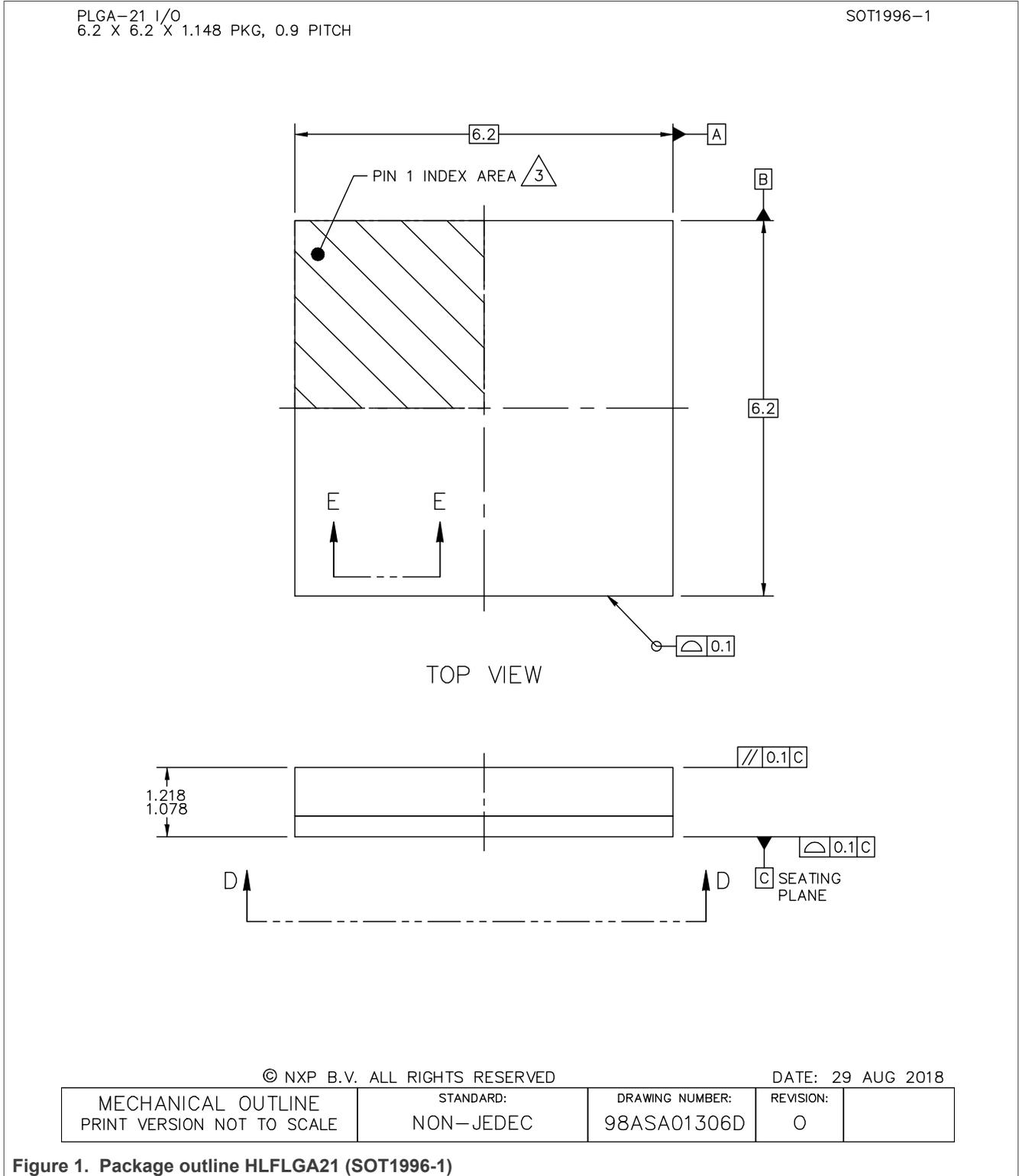
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	6.1	6.2	6.3	mm
package width	6.1	6.2	6.3	mm
seated height	1.078	1.148	1.218	mm
nominal pitch	-	0.9	-	mm
actual quantity of termination	-	21	-	

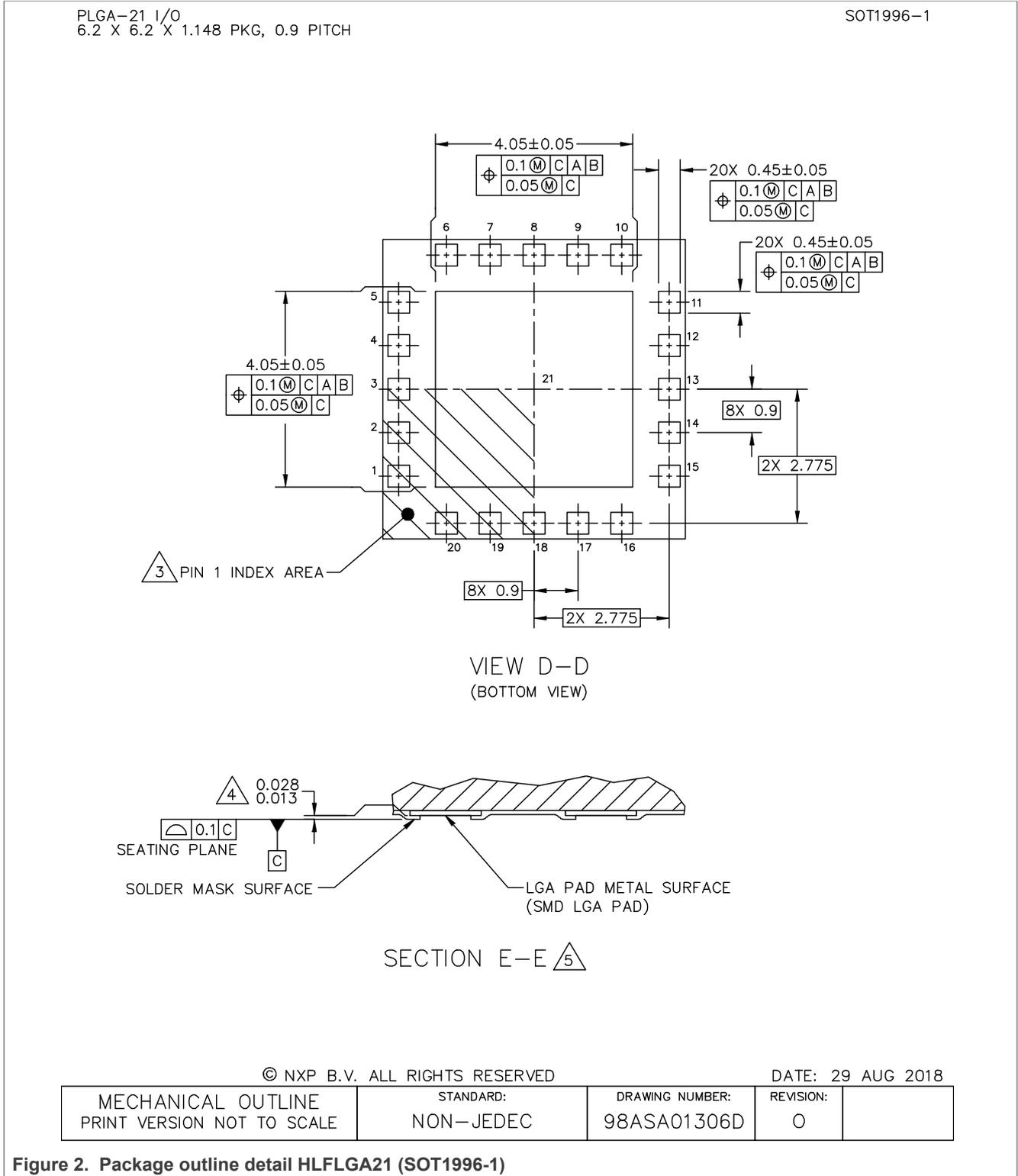


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2 Package outline

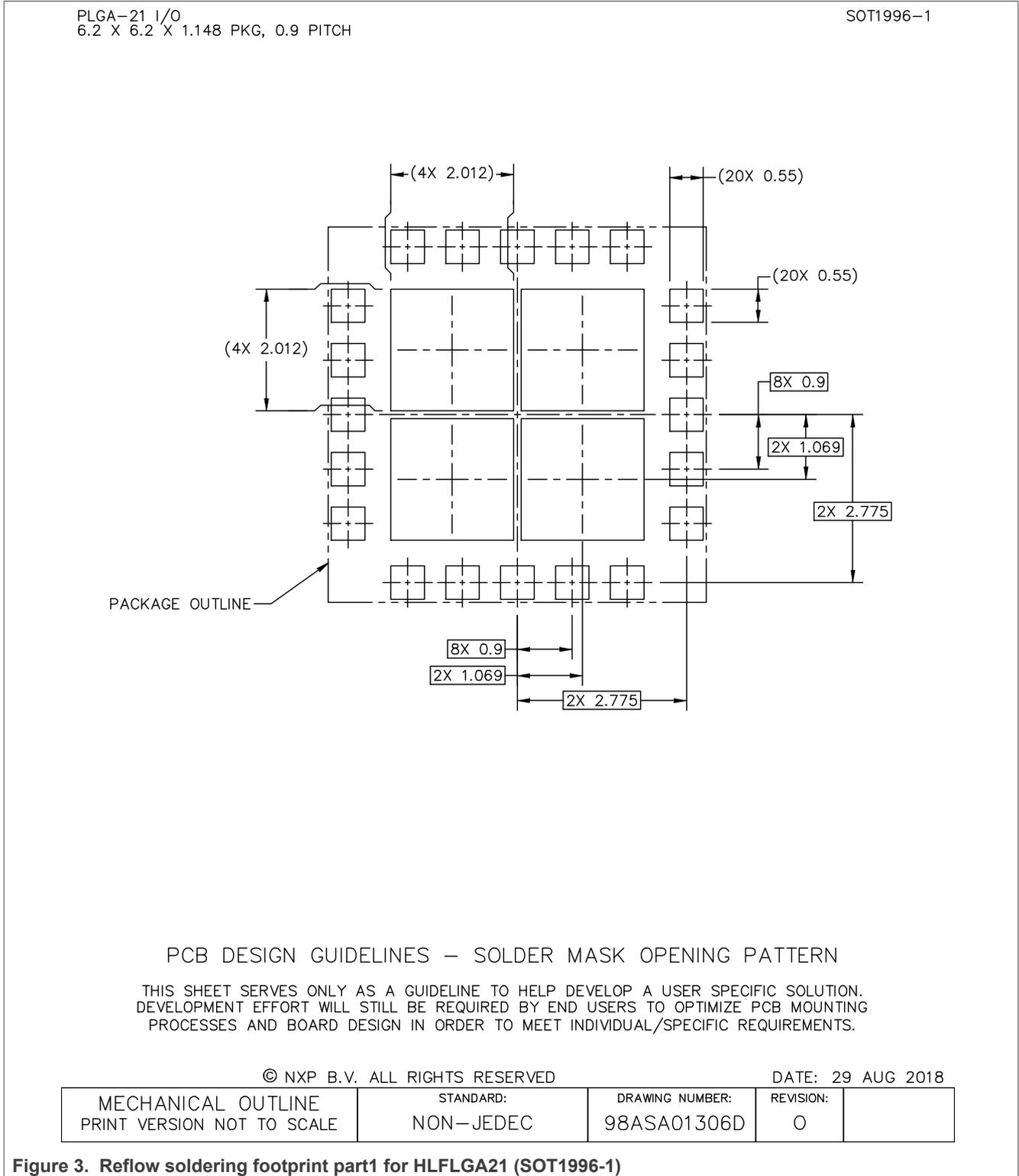


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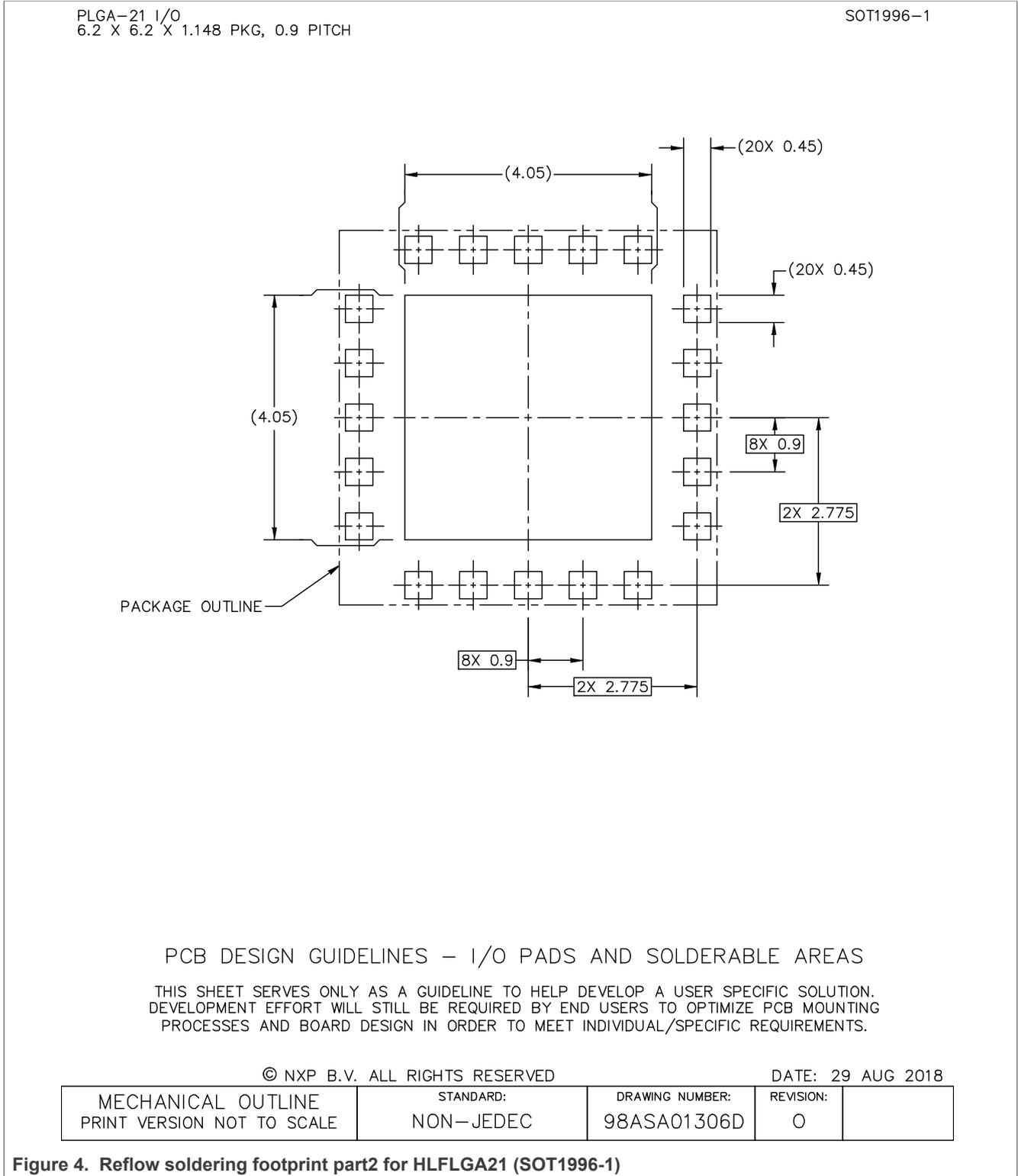


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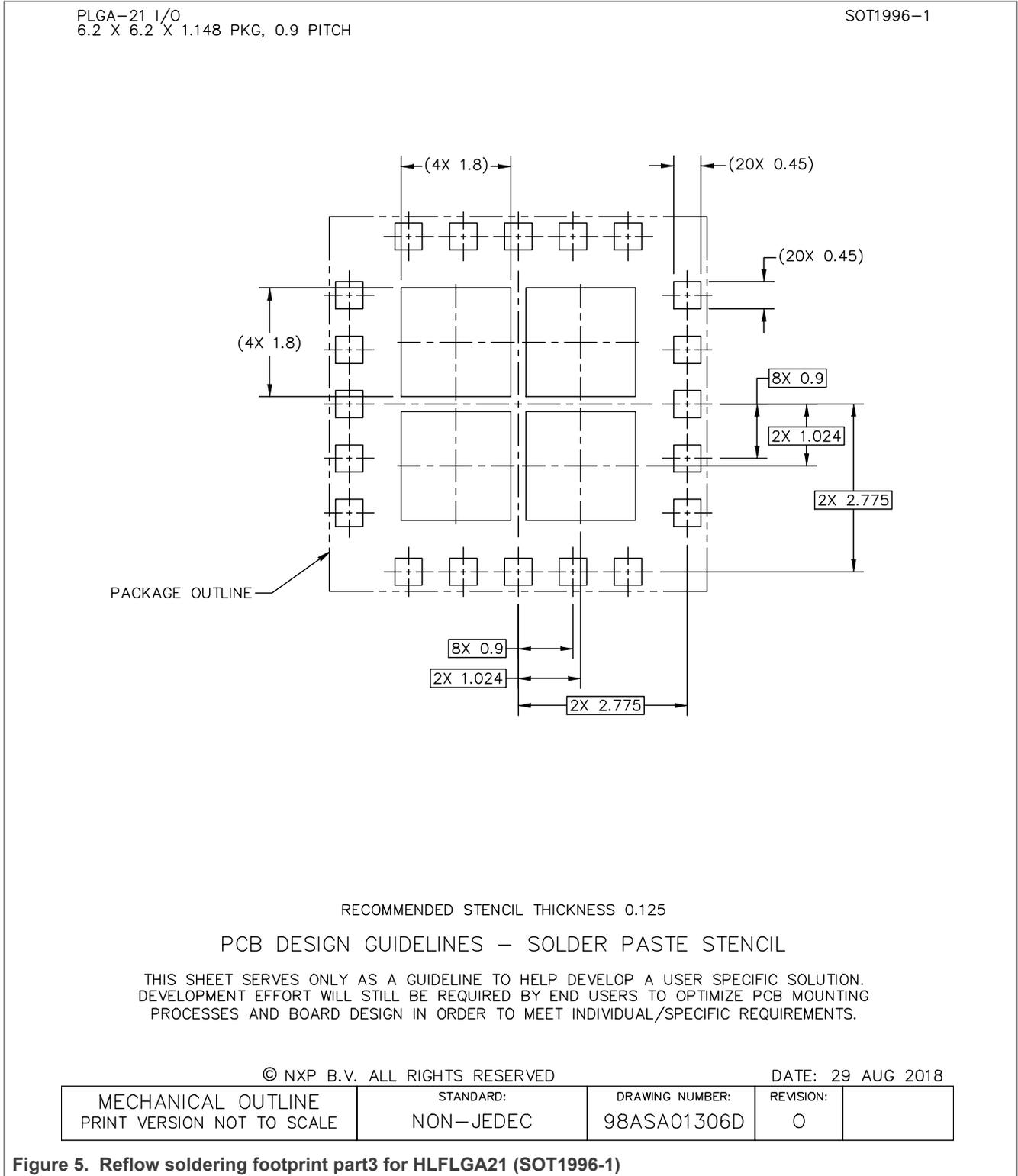
3 Soldering



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6.2 mm x 6.2 mm x 1.148 mm body**

PLGA-21 I/O  
6.2 X 6.2 X 1.148 PKG, 0.9 PITCH

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NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. DIMENSION APPLIES TO ALL LEADS AND FLAG.
5. THE BOTTOM VIEW SHOWS THE SOLDERABLE AREA OF THE PADS. THE CENTER PAD (PIN 21) AND THE PERIPHERAL PADS ARE SOLDER MASK DEFINED (SMD).

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DATE: 29 AUG 2018

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA01306D	REVISION: 0	
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**Figure 6. Package outline note HLFLGA21(SOT1996-1)**

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## 4 Legal information

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